Double-Data-Rate OPI OctaBus PSRAM

Specifications

- **Single Supply Voltage**
  - V_{DD} =1.62 to 1.98V
  - V_{DDQ} =1.62 to 1.98V
- **Interface**: Octal Peripheral interface (OPI) with OctaBus mode, two bytes transfers per one clock cycle
- **Performance**: Clock rate up to 200MHz, 400MB/s read/write throughput
- **Organization**: 64Mb, 8M x 8bits with 1024 byte page size
  - Column address: AY0 to AY9
  - Row address: AX0 to AX12
- **Refresh**: Self-managed
- **Operating Temperature Range**
  - Tc= -40°C to +85°C (standard range)
  - Tc= -40°C to +105°C (extended range)
- **Maximum Standby Current**
  - 300µA @ 105°C
  - 200µA @ 85°C
- **Typical Standby Current**
  - 20 µA @ 25°C (Halfsleep™ Mode with data retained)

Features

- **Low Power Features**
  - Auto Temperature Compensated Self-Refresh (ATCSR) by built-in temperature sensor
  - Ultra Low Power Halfsleep™ mode with data retained
- **Software Reset**
- **Reset Pin Available**
- **Output Driver LVCMOS** with programmable drive strength
- **Data Mask (DM)** for write data
- **Data strobe (DQS)** enabled high speed read operation
- **Register Configurable** write and read initial latencies
- **Write Burst Length**
  - maximum 1024 Bytes
  - minimum 2 Bytes
- **Wrap & Hybrid Burst** in 16/32/64/128 lengths.
- **Linear Burst Command** (wraps at page boundary)

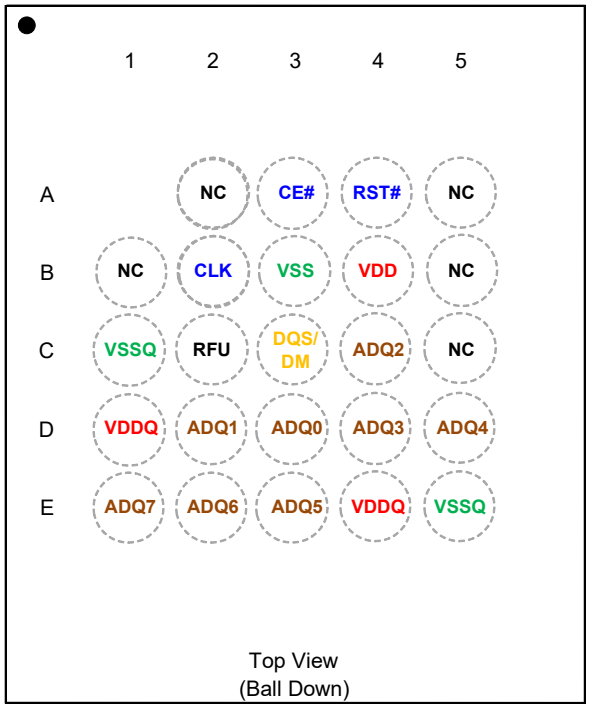
Table of Contents

1 Table of Contents

2 Package Information

The APS6408L-OCHx is available in mini-BGA 24B package 6 x 8 x 1.2mm, ball pitch 1.0mm, ball size 0.4mm, package code “BA”.

- Ball Assignment for MINI-BGA 24B



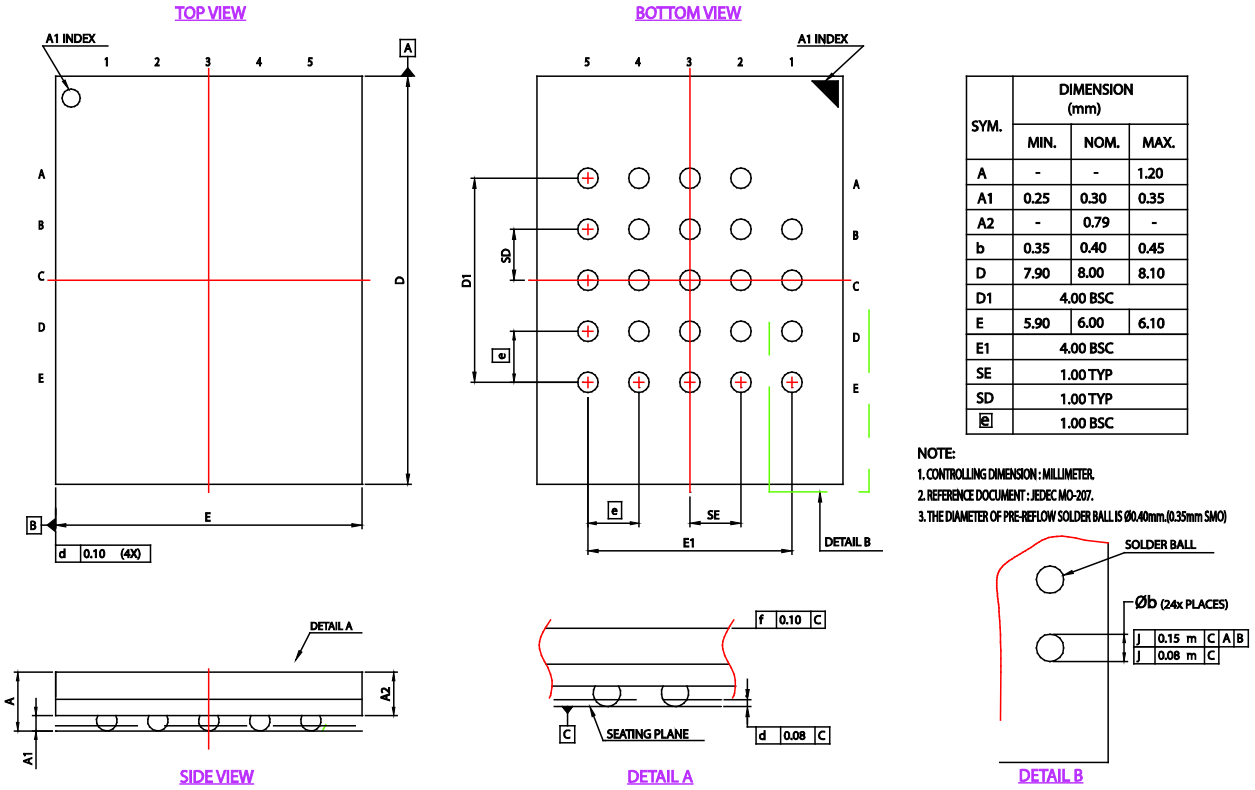
(6x8x1.2mm)(P1.0)(B0.4)

Note:

1. Part Number APS6408L-OCH-BA for 64Mb.
2. RFU: Reserved for future use, which is reserved for 2nd CE#.
3. NC: No internal connection.

3 Package Outline Drawing

Package code “BA”



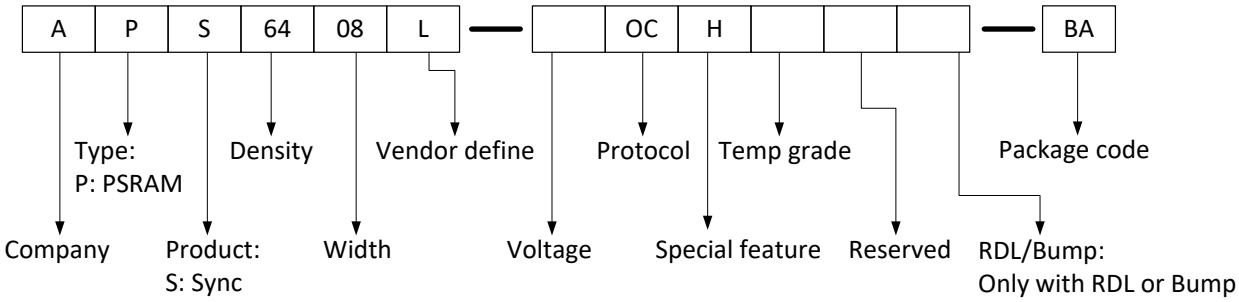
SYM.	DIMENSION (mm)		
	MIN.	NOM.	MAX.
A	-	-	1.20
A1	0.25	0.30	0.35
A2	-	0.79	-
b	0.35	0.40	0.45
D	7.90	8.00	8.10
D1		4.00 BSC	
E	5.90	6.00	6.10
E1		4.00 BSC	
SE		1.00 TYP	
SD		1.00 TYP	
e		1.00 BSC	

NOTE:
1. CONTROLLING DIMENSION : MILLIMETER.
2. REFERENCE DOCUMENT : JEDEC MO-207.
3. THE DIAMETER OF PRE-REFLOW SOLDER BALL IS Ø0.40mm.(0.35mm SMO)

4 Ordering Information

Table 1: Ordering Information

Part Number	*Temperature Range*	*Max Frequency*	*Note*
APS6408L-OCH-BA	Tc=-40°C to +85°C	200 MHz	BGA 24B
APS6408L-OCHX-BA	Tc=-40°C to +105°C	200 MHz	BGA 24B



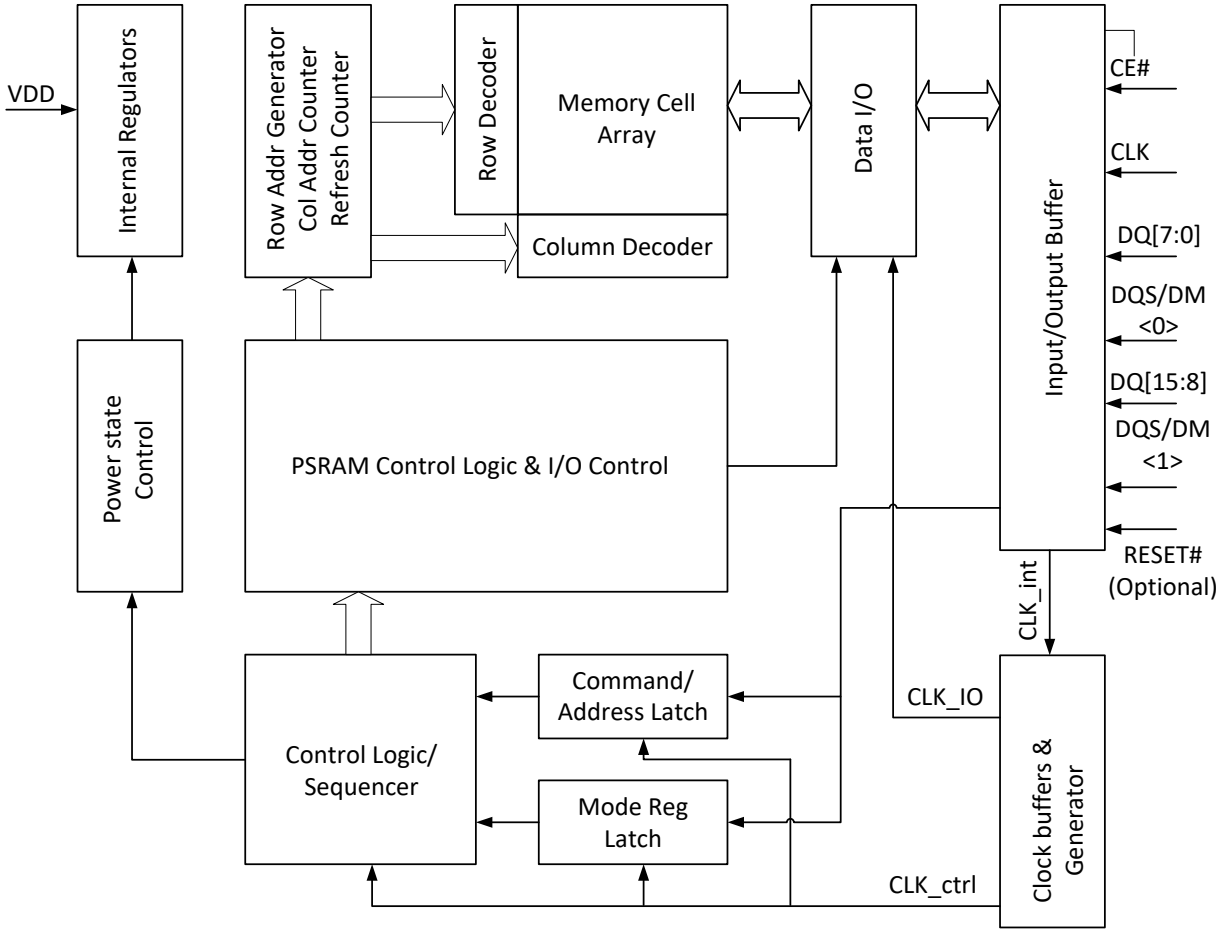
5 Signal Table

All signals are listed in Table 2.

Table 2: Signals Table

Symbol	*Type*	*Description*	*Comments*
V_{DD}	Power	Core supply 1.8V	
V_{DDQ}	Power	IO supply 1.8V	
V_{SS}	Ground	Core supply ground	
V_{SSQ}	Ground	IO supply ground	
A/DQ[7:0]	IO	Address/DQ bus [7:0]	
DQS/DM	IO	DQ strobe clock during reads, Data mask during writes. DM is active high. DM=1 means “do not write”.	
CE#	Input	Chip select, active low. When CE#=1, chip is in standby state.	
CLK	Input	Clock signal	
RESET#	Input	Reset signal, active low. Optional, as the pad is internally tied to a weak pull-up and can be left floating.	

6 Block diagram



7 Power-Up Initialization

Octal DDR products include an on-chip voltage sensor used to start the self-initialization process. V_{DD} and V_{DDQ} must be applied simultaneously. When they reach a stable level at or above minimum V_{DD}, the device is in Phase 1 and will require 150µs to complete its self-initialization process. The user can then proceed to Phase 2 of the initialization described in section 7.1.

During Phase 1 CE# should remain HIGH (track V_{DD} within 200mV); CLK should remain LOW.

After Phase 2 is complete the device is ready for operation, however Halfsleep™ entry and Deep Power Down (DPD) entry are not available until Halfsleep™ Power Up (tHSPU) or DPD Power Up (tDPDp) durations are observed.

7.1 Power-Up Initialization Method 1 (via. RESET# pin)

The RESET# pin can be used to initialize the device during Phase 2 as follows:

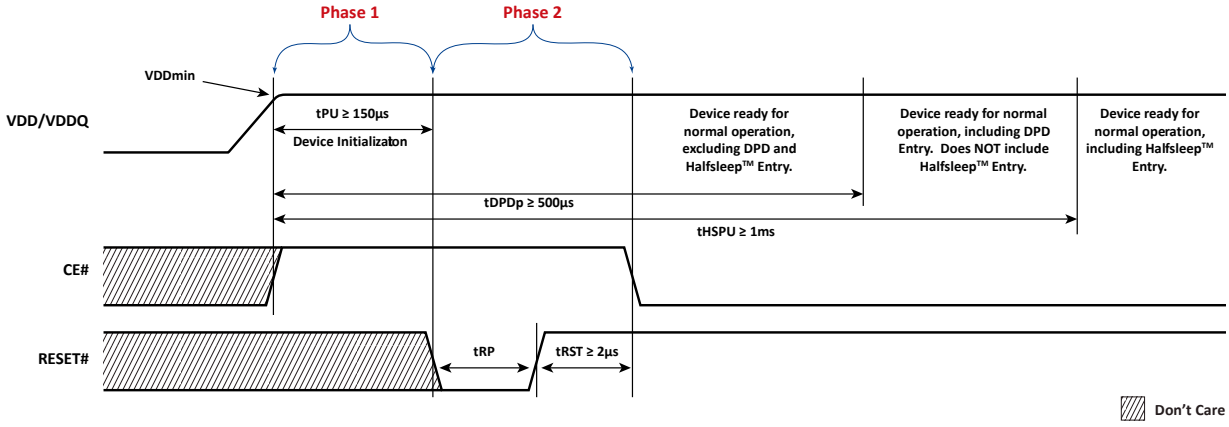


Figure 1. Power-Up Initialization Method 1 RESET#

The RESET# pin can also be used at any time when CE#=1 after the device is initialized to reset all register contents. Memory content is not guaranteed. Timing requirements for RESET# usage are shown below.

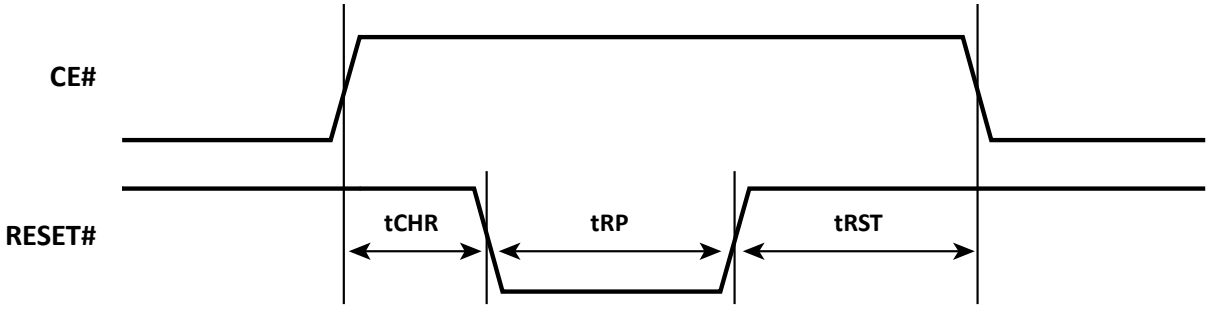


Figure 2. RESET# Timing

7.2 Power-Up Initialization Method 2 (via. Global Reset)

As an alternate power-up initialization method, after the Phase 1 150µs period the Global Reset command can also be used to reset the device in Phase 2 as follows:

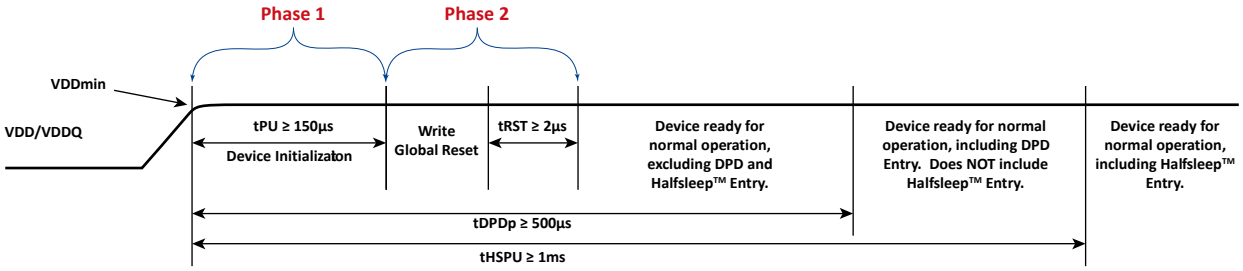


Figure 3. Power-Up Initialization Method 2 Timing with Global Reset

The Global Reset command resets all register contents. Memory content is not guaranteed. The command frame is 4 clocked CE lows. The Global Reset command sequence is shown below. Note that Global Reset command can be used ONLY as Power-up initialization.

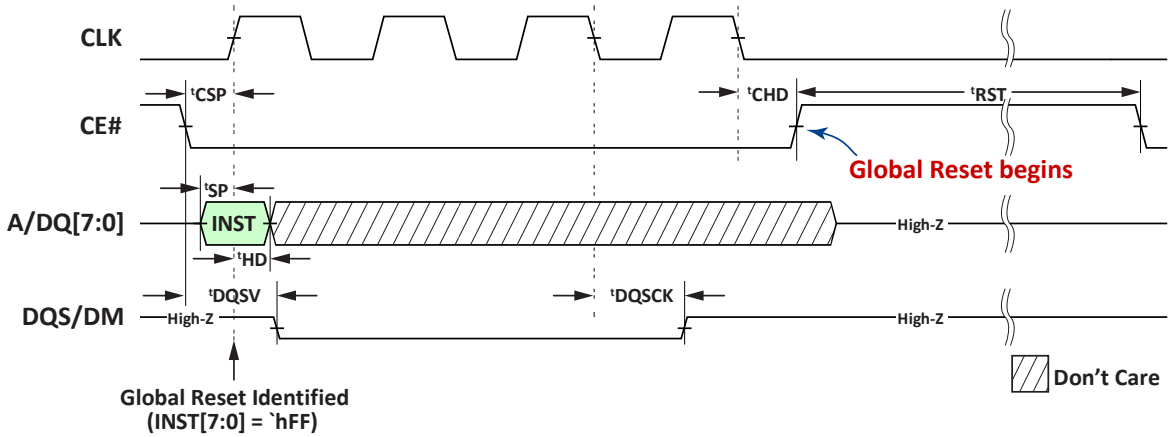


Figure 4: Global Reset

8 Interface Description

8.1 Address Space

Octal DDR PSRAM device is byte-addressable. Memory accesses are required to start on even addresses (A[0]='0).

8.2 Burst Type & Length

Read and write operations are always in wrap mode within 16, 32, 64, 128 or 1K (see Table 8). Bursts can start on any even address. Write Burst Length has a minimum of 2 bytes (1 rising CLK and 1 falling CLK edge). Read has no minimum length. Both write and read have no restriction on maximum Burst Length as long as tCEM is met.

8.3 Command/Address Latching

After CE# goes LOW, instruction code is latched on 1st CLK rising edge. Row Access (RA) address is latched on the 3rd & 4th edges (2nd CLK rising edge, 2nd CLK falling edge), while Column Access (CA) address is latched on the 5th & 6th CLK edges (3rd CLK rising edge, 3rd CLK falling edge).

	1st CLK		2nd CLK		3rd CLK	
Pin	⌐	¬	⌐	¬	⌐	¬
A/DQ[7]	INST[7]	×	rsvd.	RA[7]	CA[9]	rsvd.
A/DQ[6]	INST[6]	×	rsvd.	RA[6]	CA[8]	rsvd.
A/DQ[5]	INST[5]	×	rsvd.	RA[5]	CA[7]	rsvd.
A/DQ[4]	INST[4]	×	RA[12]	RA[4]	CA[6]	rsvd.
A/DQ[3]	INST[3]	×	RA[11]	RA[3]	CA[5]	CA[3]
A/DQ[2]	INST[2]	×	RA[10]	RA[2]	CA[4]	CA[2]
A/DQ[1]	INST[1]	×	RA[9]	RA[1]	rsvd.	CA[1]
A/DQ[0]	INST[0]	×	RA[8]	RA[0]	rsvd.	CA[0]

Remarks: × = don't care (V_{IH}/V_{IL})

During the Command/Address cycles (first three clocks) DQS/DM will be driven low by the PSRAM for all operations.

8.4 Command Truth Table

The Octal DDR PSRAM recognizes the following commands specified on the INST (Instruction) cycle defined by the Address/DQ pins.

	1st CLK		2nd CLK		3rd CLK	
Command	⌐	¬	⌐	¬	⌐	¬
Sync Read	80h	×	A3	A2	A1	A0
Sync Write	00h	×	A3	A2	A1	A0
Sync Read (Linear Burst)	A0h	×	A3	A2	A1	A0
Sync Write (Linear Burst)	20h	×	A3	A2	A1	A0
ID Register Read	C0h or E0h	×	00h	00h	00h	00h
Mode Register Read	C0h or E0h	×	00h	04h	00h	00h
Mode Register Write	40h or 60h	×	00h	04h	00h	00h
Halfsleep™ Entry	40h or 60h	×	00h	04h	00h	06h
Global Reset	FFh	×				

Remarks:
× = don't care (V_{IH}/V_{IL})
A3 = RA[max:8], unused address bits are reserved
A2 = RA[7:0]
A1 = {CA[9:4], 2xRsvd.}
A0 = {4xRsvd., CA[3:0]}
MA = Mode Register Address

Notes: 1) Default Burst Type set in Mode Register is 32 Byte Wrap

8.5 Read Operation

After address latching, the device initializes DQS/DM to '0 from CLK rising edge of the 3rd clock cycle (A1). See Figure 5 below.

Output data is available after LC cycles, as shown in Figure 6 & Figure 7, LC is latency configuration code as defined in Table 5 and Table 6. When data is valid, A/DQ[7:0] and DQS/DM follow the timing specified in Figure 8. Synchronous timing parameters are shown in Table 11 & Table 12

In case of internal refresh insertion, variable latency output data is delayed by (LCx2) latency cycles as shown in Figure 6. The 1st DQS/DM rising edge after read pre-amble will indicate the beginning of valid data.

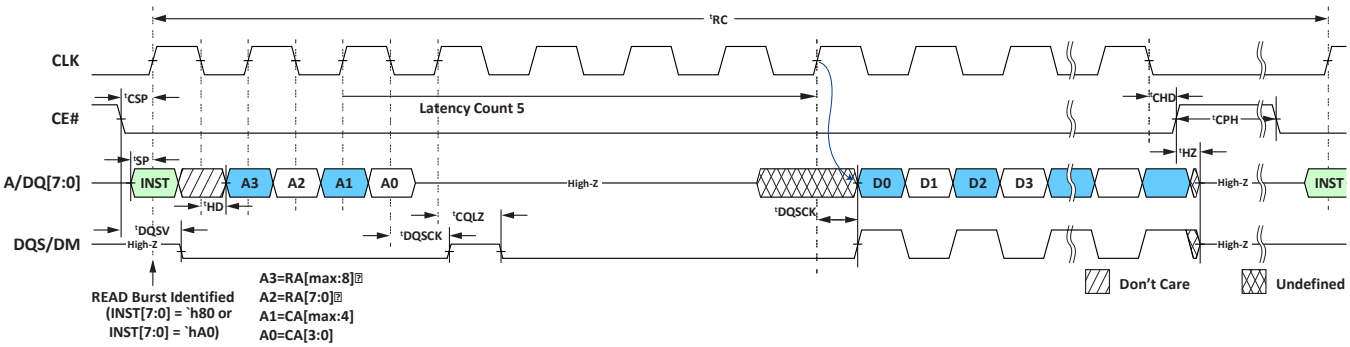


Figure 5: Synchronous Read

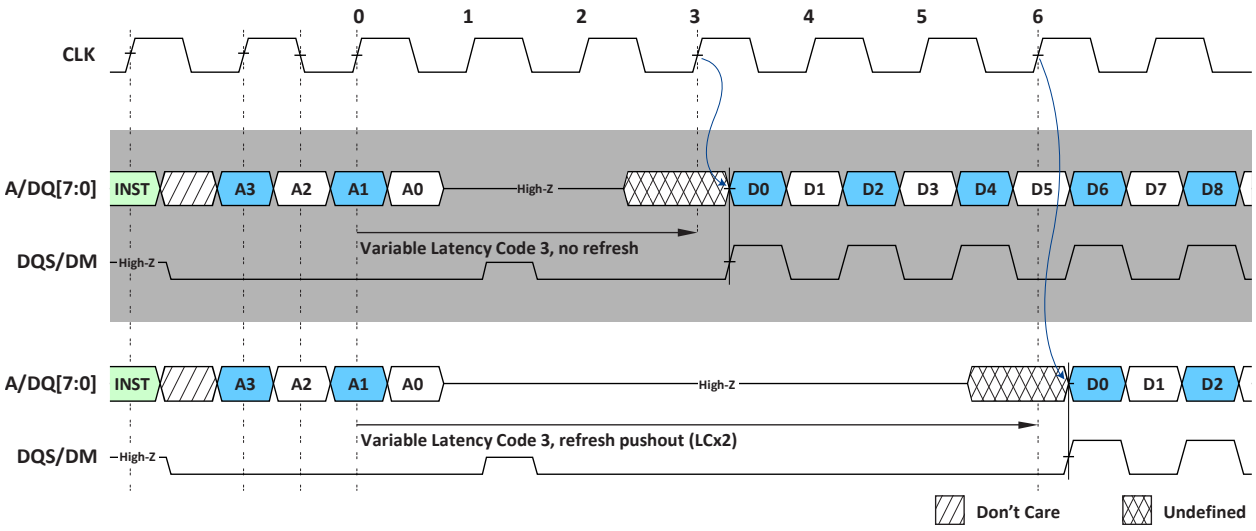


Figure 6: Variable Read Latency Refresh Pushout

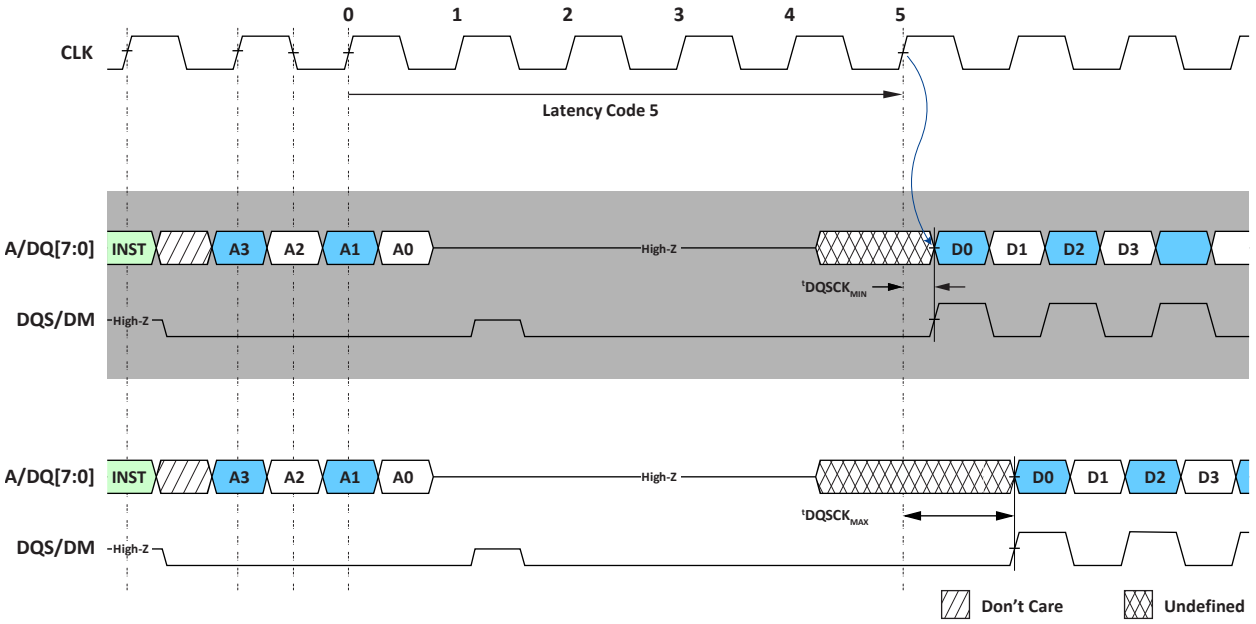


Figure 7: Read Latency & tDQSCK

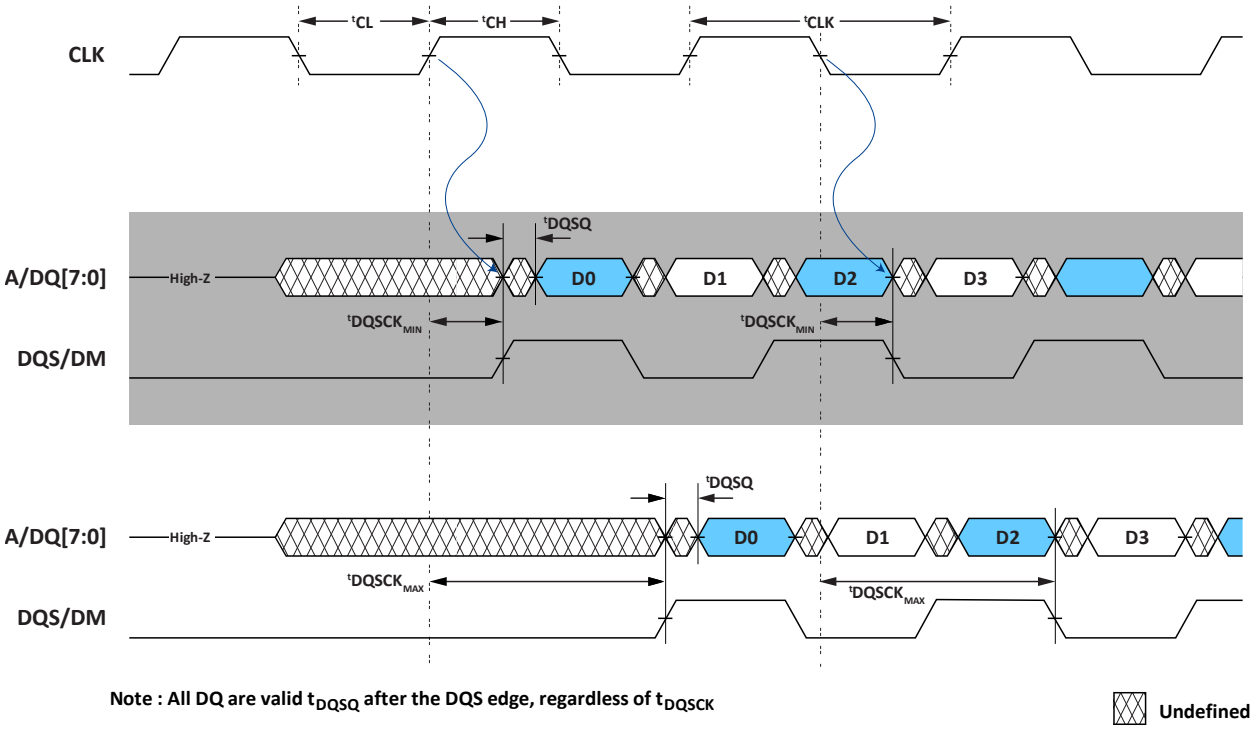


Figure 8: Read DQS/DM & DQ timing

8.6 Write Operation

A minimum of 2 bytes of data must be input in a write operation. In the case of consecutive short burst writes, tRC must be met by issuing additional CE# high time between operations. Single-byte write operations can be performed by masking the un-written byte with DQS/DM as shown in Figure 10.

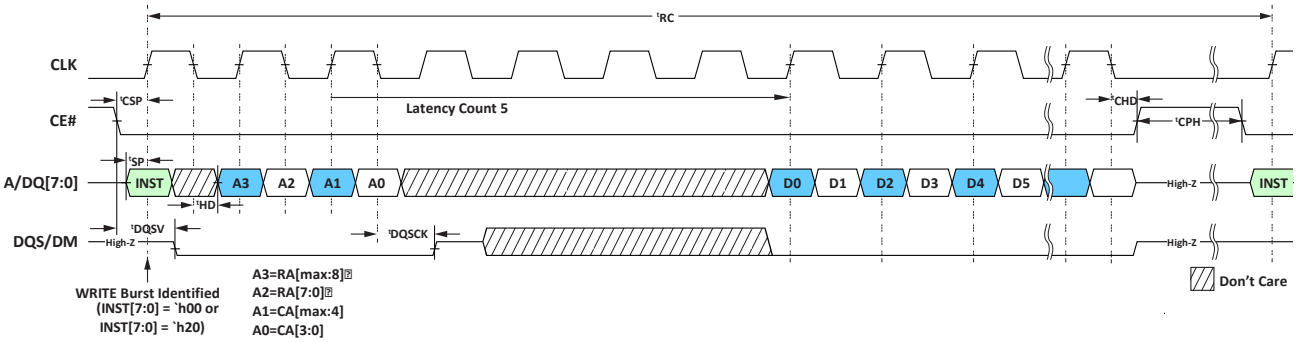


Figure 9: Synchronous Write Unmasked Example

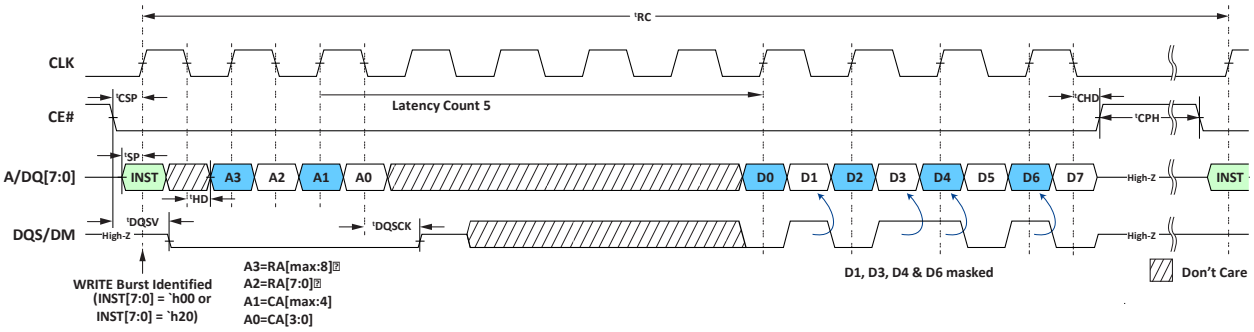


Figure 10: Synchronous Write Masking Example

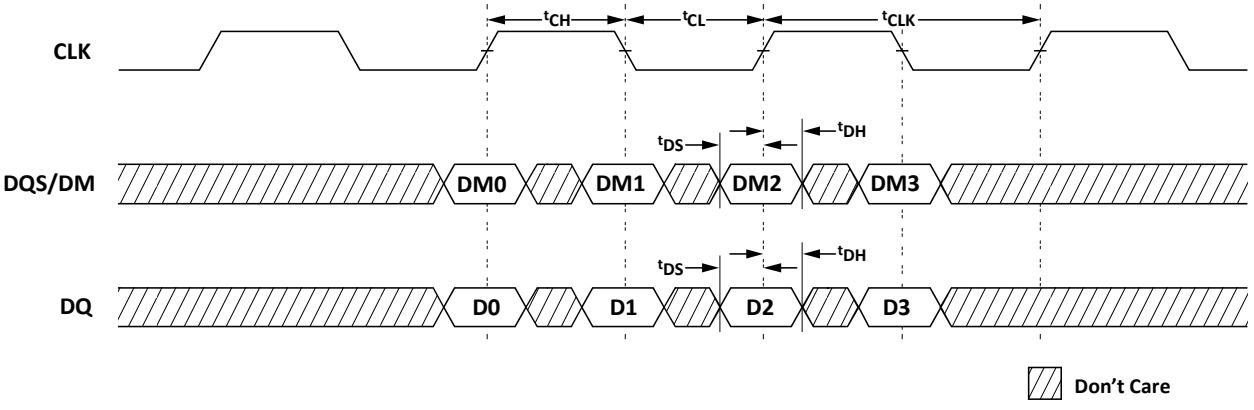


Figure 11: Write DQS/DM & DQ Timing

8.7 Control Registers

Register Read is shown below. Register reads are always LC latency cycles. Register Address in command determines which Register is read from.

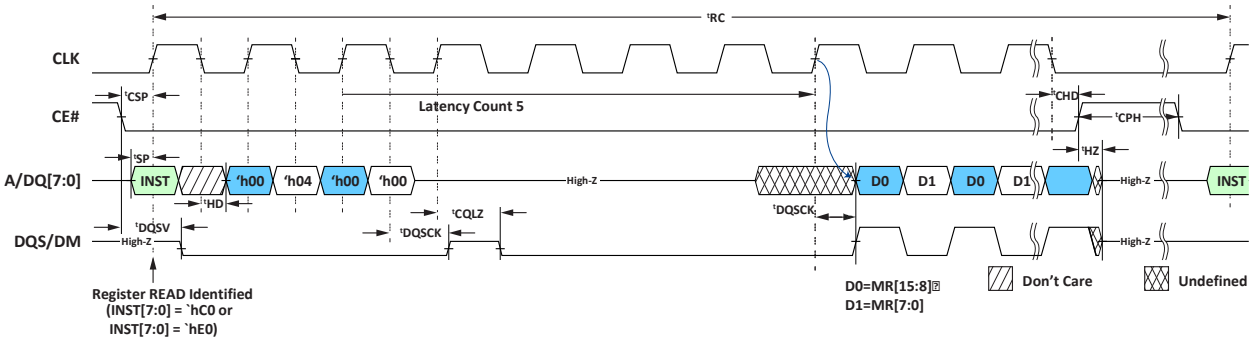


Figure 12: Mode Register Read

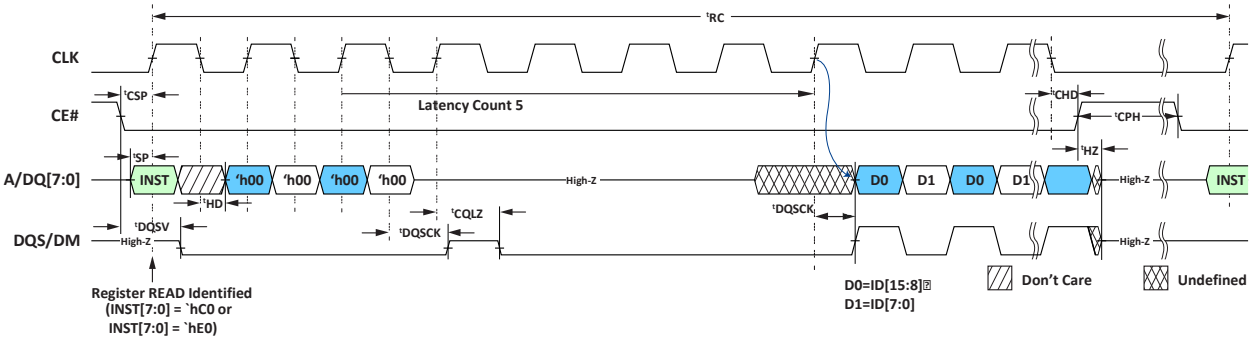


Figure 13: ID Register Read

Register Write is shown below. Register Writes are always 0 latency cycle.

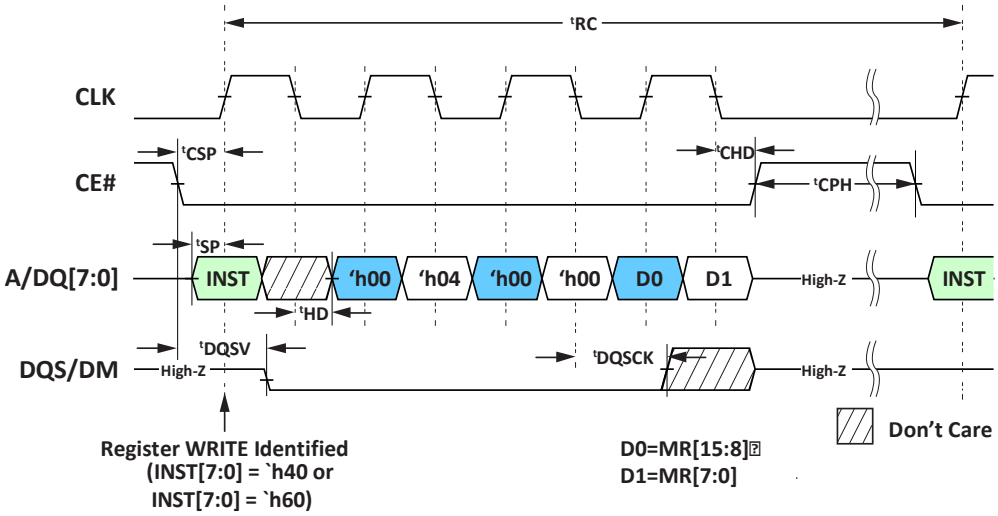


Figure 14: Register Write

ID & Mode Register mappings are shown in Table 3 & Table 4.

Table 3: ID Register Table

Bit	Purpose	Settings
15	KBD	0 - Good Die 1 - Known Bad Die
14-13	reserved	00
12-8	Row Address MSB	01100 - 13 row address bits (64M) 01101 - 14 row address bits (128M)
7-4	Col Address MSB	1001 - 10 column address bits
3-0	Vendor	1101 - AP Memory

Table 4: Mode Register Table

Bit	Purpose	Settings
15	Deep Power Down Enable	0 - Deep Power Down Entry 1 - Normal Operation (default)
14-12	Drive Strength	see Table 7
11-8	reserved	
7-4	Latency Code	see Table 5&6
3	Latency Type	0 - Variable Latency (default) 1 - Fixed Latency
2	Burst Type	0 - Wrapped (default) 1 - Hybrid Continuous
1-0	Burst Length	00 - 128 bytes 01 - 64 bytes 10 - 32 bytes (default) 11 - 16 bytes

Table 5: Latency Configuration Codes MR[7:4]

VL Codes (MR[3]=0)			*FL Codes (MR[3]=1)*	*Max Input CLK Freq (MHz)*	
MR[7:4]	*No Refresh (LC)*	*Refresh (LCx2)*	*(LCx2)*	*Standard*	*Extended*
0000	3	6	6	66	66
0001	4	8	8	104	104
0010	5	10	10	133	133
0011	6	12	12	166	166
0100	7	14	14	200	200
0101	8 (default)	16	16	200	200
others	Reserved	-	-	-	-

Table 6: Operation Latency Code Table

Type	*Operation*	*VL (default)*		*FL*
		No Refresh	*Refresh*	
Memory	Read	LC	LCx2	LCx2
	Write	LC		LC
Register	Read	LC		LC
	Write	0		0

Table 7: Drive Strength Codes MR [14:12]

Codes	*Drive Strength*
‘000	100Ω
‘001	66Ω
‘010	50Ω
‘011	40Ω
‘10x	33Ω
‘11x	25Ω (default)

Table 8: Burst Type MR[2], Burst Length MR[1:0], & Linear Burst

By default the device powers up in 32 Byte Wrap. In non-Hybrid burst (MR[2]=0), MR[1:0] sets the burst address space in which the device will continually wrap within. If Hybrid Burst Wrap is selected (MR[2]=1), the device will burst through the initial wrapped Burst Length once, then continue to burst incrementally up to maximum column address (1K) before wrapping around within the entire column address space. Burst Length (MR[1:0]) can be set to 16,32,64 & 128 bytes.

MR[2]	*MR [1:0]*	*Burst Length*	*Example of Sequence of Bytes During Wrap*	
			Starting Address	*Byte Sequence*
'0	'00	128 Byte Wrap	4	[4,5,6,…127,0,1,2,…]
'0	'01	64 Byte Wrap	4	[4,5,6,…63,0,1,2,…]
'0	'10	32 Byte Wrap (default)	4	[4,5,6,…31,0,1,2,…]
'0	'11	16 Byte Wrap	4	[4,5,6,…15,0,1,2,…]
'1	'00	128 Byte Hybrid Wrap	2	[2,3,4,…127,0,1],128,129…1023,0,1,…
'1	'01	64 Byte Hybrid Wrap	2	[2,3,4,…63,0,1],64,65,66,…1023,0,1,…
'1	'10	32 Byte Hybrid Wrap	2	[2,3,4,…31,0,1],32,33,34,…1023,0,1,…
'1	'11	16 Byte Hybrid Wrap	2	[2,3,4,…15,0,1],16,17,18,…1023,0,1,…

The Linear Burst Command (INST[5:0]=6'b10_0000) forces the current array read or write to do 1K Byte Wrap. The burst continues linearly from the starting address and at the end of the page it wraps back to the beginning of the page. This special burst instruction can be used on both array writes and reads. A new command is needed to access a different page.

8.8 Deep Power Down Mode

Deep Power Down Mode (DPD) is a feature which puts the device in an ultra-low power state. DPD Mode Entry is entered by using Register Write to write a 0 into MR[15]. CE# going high initiates the DPD Mode and must be maintained for the minimum duration of tDPD. The Deep Power Down Entry command sequence is shown below.

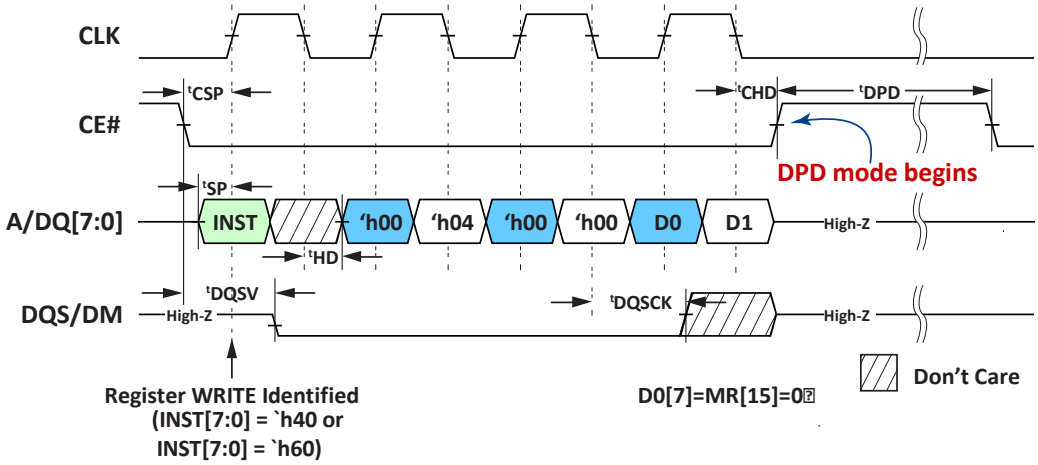


Figure 15: Deep Power Down Entry Write

Deep Power Down Exit is initiated by a low pulsed CE# or RESET#. After a CE# DPD Exit, CE# must be held high until the first operation begins (observing minimum tXDPD).

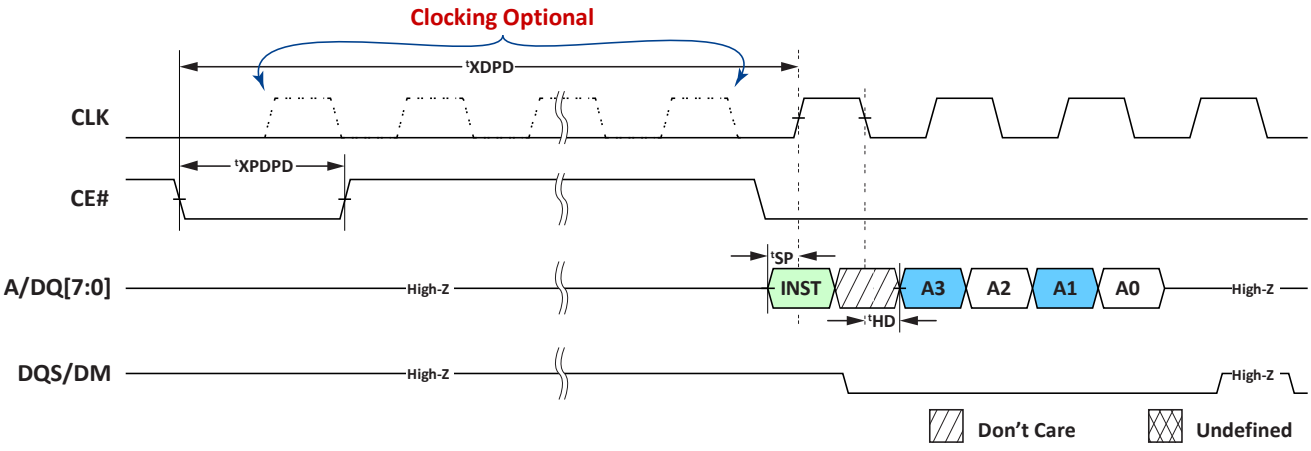


Figure 16: Deep Power Down Exit with CE# (Read Operation shown as example)

After a RESET# DPD exit, CE# and RESET# must be held high until the first operation begins (observing minimum tRCH).

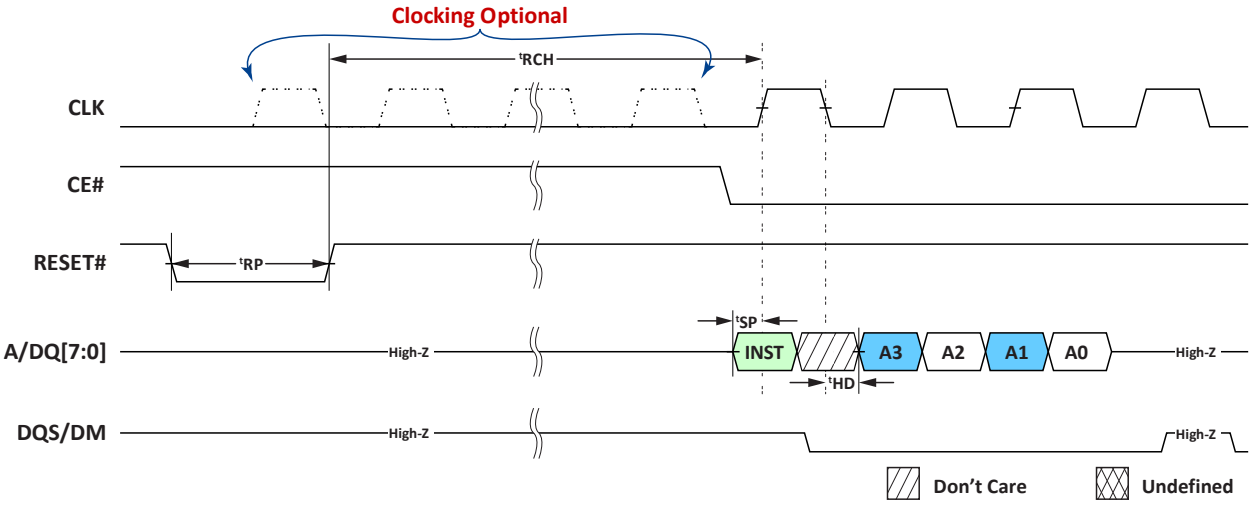


Figure 17: Deep Power Down Exit with RESET# (Read Operation shown as example)

Register values are retained in DPD Mode but memory content is not. However, if a RESET# low is used to exit DPD, register values are also reset to defaults. tDPDp is minimum period between two DPD Modes (measured from DPD exit to the next DPD entry) as well as from the initial powerup to the first DPD entry.

8.9 Halfsleep™ Mode

Halfsleep™ Mode is a feature which puts the device in an ultra-low power state, while the stored data is retained. Halfsleep™ Mode Entry is entered by writing 8'hF0 into MR6. CE# going high initiates the Halfsleep™ mode and must be maintained for the minimum duration of tHS. The Halfsleep™ Entry command sequence is shown below.

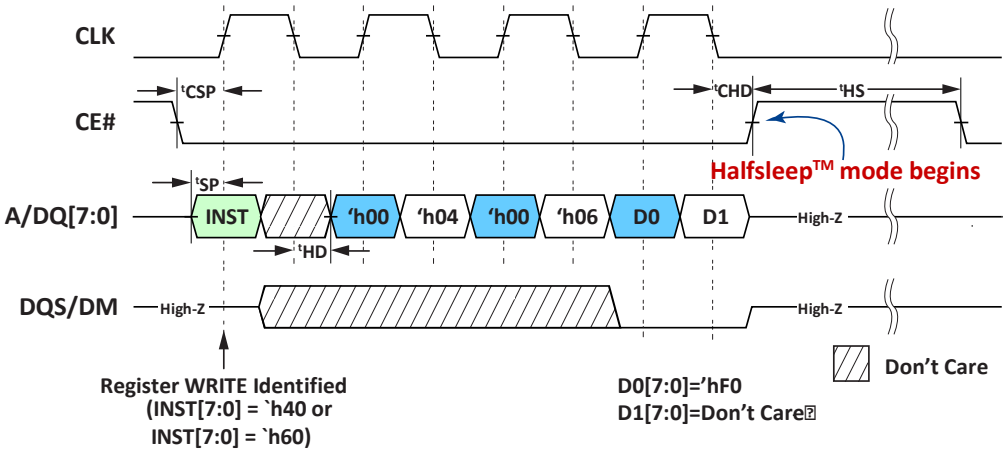


Figure 18: Halfsleep™ Entry

Halfsleep™ Exit is initiated by a low pulsed CE#. Afterwards, CE# should be held high until the first operation begins (observing minimum tXHS).

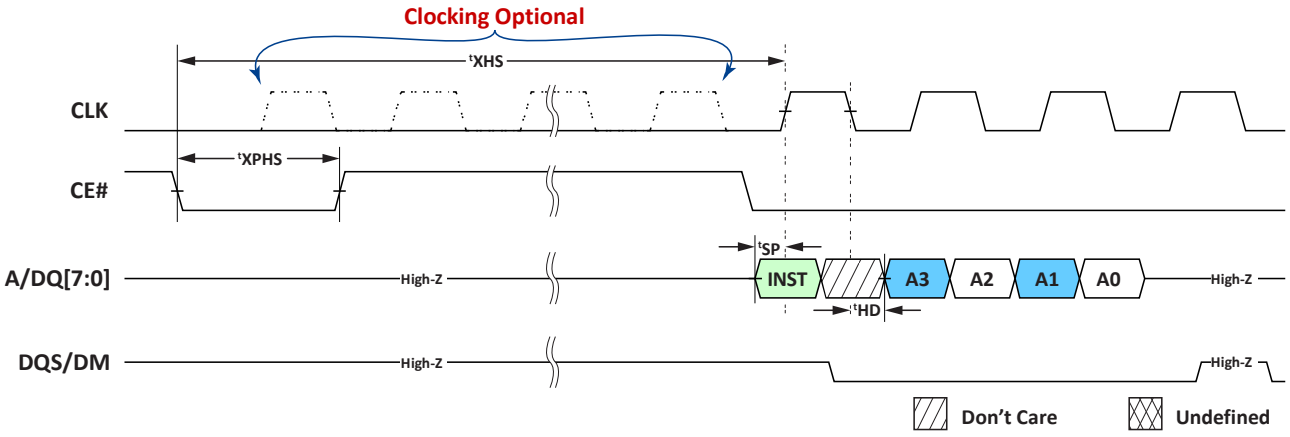


Figure 19: Halfsleep™ Exit

9 Electrical Specifications:

9.1 Absolute Maximum Ratings

Table 9: Absolute Maximum Ratings

Parameter	*Symbol*	*Rating*	*Unit*	*Notes*
Voltage to any ball except V_{DD}, V_{DDQ} relative to V_{SS}	VT	-0.4 to V_{DD}/V_{DDQ}+0.4	V	
Voltage on V_{DD} supply relative to V_{SS}	V_{DD}	-0.4 to +2.45	V	
Voltage on V_{DDQ} supply relative to V_{SS}	V_{DDQ}	-0.4 to +2.45	V	
Storage Temperature	T_{STG}	-55 to +150	°C	1

Notes 1: Storage temperature refers to the case surface temperature on the center/top side of the PSRAM.

Caution:
Exposing the device to stress above those listed in Absolute Maximum Ratings could cause permanent damage. The device is not meant to be operated under conditions outside the limits described in the operational section of this specification. Exposure to Absolute Maximum Rating conditions for extended periods may affect device reliability.

9.2 Input Signal Overshoot

During DC conditions, input or I/O signals should remain equal to or between VSS and VDD. During voltage transitions, inputs or I/Os may negative overshoot VSS to -1.0V or positive overshoot to VDD +1.0V, for periods up to 20 ns.

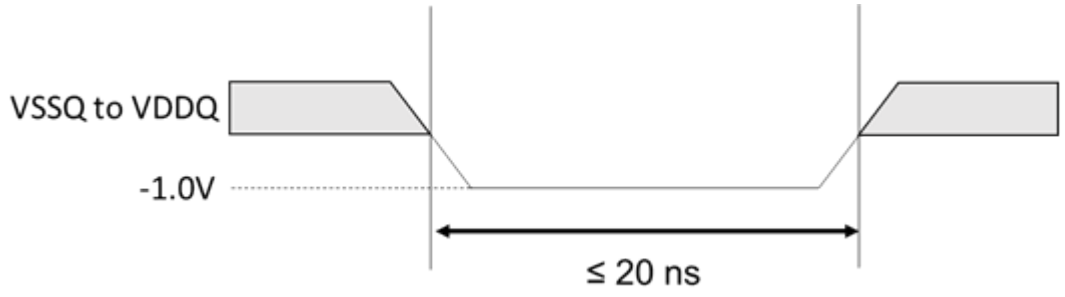


Figure 20 Maximum Negative Overshoot Waveform

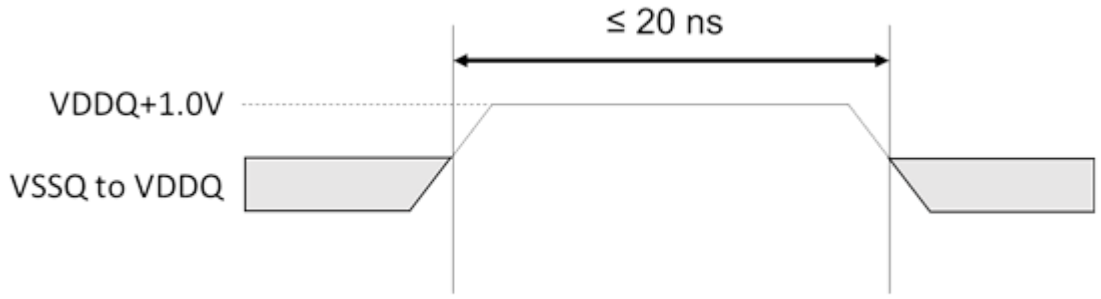


Figure 21 Maximum Positive Overshoot Waveform

9.3 Pin Capacitance

Table 10: Package Pin Capacitance

Parameter	Symbol	Min	Max	Unit	Notes
Input Pin Capacitance	CIN		6	pF	VIN=0V
Output Pin Capacitance	COUT		8	pF	VOUT=0V

Note: spec'd at 25°C.

Table 11: Load Capacitance

Parameter	Symbol	Min	Max	Unit	Notes
Load Capacitance	C_L		15	pF	

Note: System C_L for the use of package.

9.4 Decoupling Capacitor Requirement

System designers need to take care of power integrity considering voltage regulator response and the memory peak currents/usage modes.

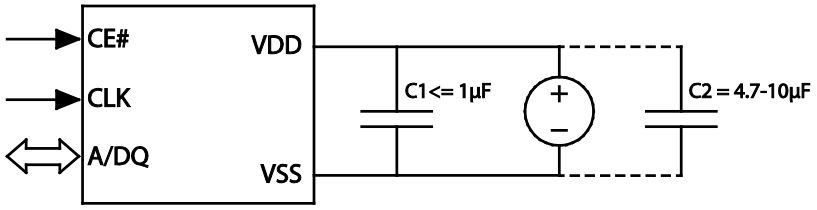


Figure 22: Decoupling Capacitor

9.4.1 Low ESR cap C1:

It is recommended to place a low ESR decoupling capacitor of <=1µF close to the device to absorb transient peaks.

9.4.2 Large cap C2:

During Half-sleep modes even though half-sleep average currents are very small (less than 100µA), device will internally have low duty cycle burst refresh for an extended period of time of a few tens of microseconds. These refresh current peaks are large. During this period if the system regulator cannot supply large peaks for several microseconds, it is important to place a 4.7µF-10µF cap to take care of burst refresh currents and replenish the charge before next burst of refreshes.

If required please contact AP Memory for further current peak details.

9.5 Operating Conditions

Table 12: Operating Characteristics

Parameter	Min	Max	Unit	Notes
Operating Temperature (extended)	-40	105	°C	
Operating Temperature (standard)	-40	85	°C	

9.6 DC Characteristics

Table 10: DC Characteristics

Symbol	Parameter	Min	Max	Unit	Notes
V_{DD}	Supply Voltage	1.62	1.98	V	
V_{DDQ}	I/O Supply Voltage	1.62	1.98	V	
V_{IH}	Input high voltage	V_{DDQ}-0.4	V_{DDQ}+0.2	V	
V_{IL}	Input low voltage	-0.2	0.4	V	
V_{OH}	Output high voltage (I_{OH}=-0.2mA)	0.8 V_{DDQ}		V	
V_{OL}	Output low voltage (I_{OL}=+0.2mA)		0.2 V_{DDQ}	V	
I_{LI}	Input leakage current		1	µA	
I_{LO}	Output leakage current		1	µA	
ICC	Read/Write @13MHz		4	mA	2
	Read/Write @133MHz		16	mA	2
	Read/Write @166MHz		19	mA	2
	Read/Write @200MHz		22	mA	2
ISB_{EXT}	Standby current (105C)		300	µA	1,3
ISB_{STD}	Standby current (85C)		200	µA	3
ISB_{STDDPD}	Standby current (Deep Power Down -40°C to +85°C)		15	µA	8

Note 1: Spec'd up to 105°C.

Note 2: Current is only characterized.

Note 3: Without CLK toggling. ISB will be higher if CLK is toggling.

Note 4: Slow Refresh.

Note 6: Current is only guaranteed after 150ms into Halfsleep™ mode.

Note 7: **Typical ISB_{STDHS} 20uA**

Note 8: **Typical mean ISB_{STDDPD} 7uA at 25°C**

9.7 AC Characteristics

Table 11: READ/WRITE Timing

		-7(133MHz)		-6(166MHz)		-5(200MHz)			
Symbol	**Parameter**	**Min**	**Max**	**Min**	**Max**	**Min**	**Max**	**Unit**	**Notes**
tCLK	CLK period	7.5		6		5		ns	
tCH/tCL	Clock high/low width	0.45	0.55	0.45	0.55	0.45	0.55	tCLK	
tKHKL	CLK rise or fall time		1.2		1		0.8	ns	
tCPH	CE# high pulse width	15		18		20		ns	Clocking
tCEM	CE# low pulse width		8		8		8	µs	Standard temp
			3		3		3	µs	Extended temp
tCEM	CE# low pulse width	3		3		3		tCLK	
tCSP	CE# setup time to CLK rising edge	2		2		2		ns	
tCHD	CE# hold time from CLK falling edge	2		2		2		ns	
tSP	Setup time to active CLK edge	0.8		0.7		0.6		ns	
tHD	Hold time from active CLK edge	0.8		0.7		0.6		ns	
tDQSV	Chip enable to DQS output low	2	6	2	6	2	6	ns	
tHZ	Chip disable to DQ/DQS output high-		6		6		6	ns	
tRC	Write Cycle	60		60		60		ns	
tRC	Read Cycle	60		60		60		ns	
tHS	Minimum Halfsleep™ duration	150		150		150		µs	
tXHS	Halfsleep™ Exit CE# low to CLK setup time	150		150		150		µs	
tXPHS	Halfsleep™ Exit CE# low pulsewidth	60		60		60		ns	
			tCEM		tCEM		tCEM	µs	Standard temp
								µs	Extended temp
tDPD	Minimum DPD Duration	500		500		500		µs	
tDPDp	Minimum period between DPD	500		500		500		µs	
tXDPD	DPD CE# low to CLK setup time	150		150		150		µs	
tXPDPD	DPD Exit CE# low pulsewidth	60		60		60		ns	
			4		4		4	µs	
tPU	Device Initialization	150		150		150		µs	
tRP	RESET# low pulse width	1		1		1		µs	
tRST	Reset to CMD valid	2		2		2		µs	
tRCH	RESET# to CMD valid	150		150		150		µs	
tCHR	Chip-disable to RESET# low	20		20		20		ns	

Table 12: DDR timing parameters

		-7(133MHz)		*-6(166MHz)*		*-5(200MHz)*			
Symbol	***Parameter***	***Min***	***Max***	***Min***	***Max***	***Min***	***Max***	***Unit***	***Notes***
tCQLZ	Clock rising edge to DQS low	1	6	1	6	1	6	ns	
tDQSCK	DQS output access time from CLK	2	5.5	2	5.5	2	5.5	ns	
tDQSQ	DQS – DQ skew		0.6		0.5		0.4	ns	
tDS	DQ and DM input setup time	0.8		0.7		0.6		ns	
tDH	DQ and DM input hold time	0.8		0.7		0.6		ns	

10 Change Log

Version	Who	Date	Description
0.5		Dec 18, 2015	Initial Release
0.6		Jan 14, 2016	Instruction bit [7] flip; added Continuous, Deep Power Down, DQS Skew, expanded WL, tCEM
0.7		Jan 15, 2016	Updated write latency table
0.8		Feb 16, 2016	Changes to match MXIC Specs
0.9		Mar 09, 2016	Correction to KGD polarity; updated tCPH; flipped DQS Pre-Cyc definition; shuffled ID Register
1.0		Apr 01, 2016	Added tCHD
1.1		Jul 15, 2016	Changed tHZ; added VL pushout waveform; added junk data to read waveforms; changed tCPH definition
1.2		Sep 28, 2016	Added cover page
1.3		Dec 21, 2016	Renamed Continuous Burst to Linear, lowered tCPH, correction to latency start in drawings; added 64Byte Burst Length command; Added DQS low pulse during command/address
1.4		May 04, 2017	Changed RESET# spec and powerup usage; Temperature range correction; Reworded burst table for clarity
1.5		Oct 08, 2019	Removed DQS Pre & PASR, added tRCH to table; 4 byte write to 2 byte; Updated tSP/tHD, tCEM, ISB #s; LC usage unification
1.51		Jan 22, 2019	Update POD of 24ball; Absolute Maximum Ratings and Package Pin Cap value
1.6		Jan 24, 2019	Removed 64Byte Burst command; Fixed MRR waveform; Corrected address A1 mapping; Updated default latency code. Added Decap section
1.61		Apr 03, 2019	Added HS mode; modified C Load; Added ISBstddpd=10uA max; noted Typical ISBSTDDPD 3uA
1.7		Aug 21, 2019	Updated Page 1; Revised Section 6 and Table 11; Noted Table 8; Updated Figure 12
1.8		Sep 28, 2019	Update header, footer and page 1; updated ICC in Table 10
1.8a		Jan 15, 2020	Updated Table of Contents, footer, section 4, Figure 19 and tHS_{min} in Table 11
1.9		Jan 22, 2020	Added Clocking optional in Figure 16, Figure 17and Figure 19

2.0		Oct 18, 2021	tCEM revised data by BD suggest (E3_OPI_64Mb/128Mb) Standard temp: 4 us -> 8 us. Extended temp: 1 us -> 3 us.
2.1	Kim/ Eric/ Wayne	Aug 15, 2022	Revised typos
2.2	Kim	Jun 28, 2023	Remove tQH on DQS & DQ timing waveform Adjust the description about interface.
2.3	Kim	Jan 19, 2024	Add chapter 9.2 input signal overshoot
2.4	Kim	Jul 31, 2024	Revised typo